



Form Type	Distribute	Version	2.0	Ref	IPC 1752A	Sectionals	Material Info	Subsectionals	D, A
Supplier Information									
Company Name	TE Connectivity	Request Document ID		Contact Name	David Benfer	Contact Title	Product Compliance Engineer		
Company Unique ID	TE Connectivity	Response Date	2014-10-30	Contact Email	dave.benfer@te.com				
Contact Phone Number	717-986-3725								
Legal Statement									
Supplier Acceptance	true								
Legal Statement									
The information provided in this document is based upon reasonable inquiry of our suppliers. This information is subject to change. This information does not in any way modify existing purchase specifications or existing contractual or other agreements terms between TE Connectivity (or its affiliated companies) and its customers.									
Product									
Manufacturer Item number	1-1634224-2	Amount	11604.0	Version	-	Identity			
Manufacturer Item Name		Weight Uom	mg	Mfr Site		Authority			
Date		UOM	Each						
EUroHS-0508	Product(s) meets EU RoHS requirements by application of the selected exemption(s) - true								
ChinaRoHS-0508	Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products - true								
EUREACH-1213	Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH - Not Available / Not Reviewed								
Product Disclosure									
Sub-Item/Material/Substance	Level	Name	Substance Category	Substance CAS	Substance Concentration	Quantity	Mass per Unit	UOM	Exemption
Material	1	Shell Plating-Ni				1.0	38.22	mg	
Substance	2	Nickel	Nickel	7440-02-0	100.0	1.0	38.22	mg	
Material	1	Contact Plating-Sn				1.0	163.8	mg	
Substance	2	Tin	Supplier	7440-31-5	100.0	1.0	163.8	mg	
Material	1	Contact Plating-Au				1.0	8.4	mg	
Substance	2	Gold	Supplier	7440-57-5	100.0	1.0	8.4	mg	
Material	1	Boardlock-Cu Compound				1.0	1599.8296	mg	
Substance	2	Zinc	Supplier	7440-66-6	37.18	1.0	594.81665	mg	
Substance	2	Aluminum	Supplier	7429-90-5	0.02	1.0	0.31997	mg	
Substance	2	Tin	Supplier	7440-31-5	0.11	1.0	1.75981	mg	
Substance	2	Copper	Supplier	7440-50-8	59.808	1.0	956.82609	mg	
Substance	2	Phosphorus	Supplier	7723-14-0	0.0020	1.0	0.03199659	mg	
Substance	2	Iron	Supplier	7439-89-6	0.38	1.0	6.07935	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	2.5	1.0	39.99574	mg	6(c) Lead as an alloying element in copper containing up to 4% lead by weight
Material	1	Contact Plating-Ni				1.0	109.2	mg	
Substance	2	Nickel	Nickel	7440-02-0	100.0	1.0	109.2	mg	
Material	1	Housing-PBT				1.0	3800.0	mg	
Substance	2	Glass, oxide, chemicals	Supplier	65997-17-3	30.0	1.0	1140.0	mg	
Substance	2	1,4-Benzenedicarb oxylic acid, polymer with 1,4-butanediol	Supplier	26062-94-2	70.0	1.0	2660.0	mg	
Material	1	SHELL				1.0	4161.78	mg	
Substance	2	Manganese	Supplier	7439-96-5	23.0	1.0	957.2094	mg	
Substance	2	Silicon	Supplier	7440-21-3	1.0	1.0	41.6178	mg	
Substance	2	Phosphorus	Supplier	7723-14-0	13.0	1.0	541.0314	mg	
Substance	2	Carbon	Supplier	7440-44-0	3.0	1.0	124.8534	mg	
Substance	2	Iron	Supplier	7439-89-6	50.0	1.0	2080.89	mg	
Substance	2	Sulfur	Supplier	7704-34-9	10.0	1.0	416.178	mg	
Material	1	Boardlock Plating-Ni				1.0	4.1704	mg	
Substance	2	Nickel	Nickel	7440-02-0	100.0	1.0	4.1704	mg	

Material	1	Contact				1.0	1718.6	mg	
Substance	2	Copper	Supplier	7440-50-8	94.016	1.0	1615.75898	mg	
Substance	2	Tin	Supplier	7440-31-5	5.81	1.0	99.85066	mg	
Substance	2	Phosphorus	Supplier	7723-14-0	0.174	1.0	2.99036	mg	